

In the Claims:

Claims 1 - 216 (Canceled)

217. (New) A structure for pattern formation adapted for optically forming a pattern, comprising: a substrate; and a photocatalyst-containing layer provided on a substrate, the photocatalyst-containing layer containing a material of which the wettability is variable through photocatalytic action upon pattern-wise exposure.

218. (New) The structure for pattern formation according to claim 217, wherein the photocatalyst-containing layer contains a compound having a siloxane bond.

219. (New) The structure for pattern formation according to claim 217, wherein the photocatalyst-containing layer contains silicone.

220. (New) The structure for pattern formation according to claim 219, wherein groups containing a fluoroalkyl group are bonded to silicon atoms in the silicone.

221. (New) The structure for pattern formation according to claim 219, wherein the silicone has been prepared from a composition containing an organoalkoxysilane.

222. (New) The structure for pattern formation according to claim 219, wherein the silicone has been prepared from a composition containing a reactive silicone compound.

223. (New) The structure for pattern formation according to claim 217, wherein the structure for pattern formation is original plate for a printing plate.

224. (New) A method for pattern formation adapted for optically forming a pattern, wherein

a structure for pattern formation, exposed pattern-wise comprises: a substrate; and a photocatalyst-containing layer provided on the substrate, the photocatalyst-containing layer containing a material of which the wettability is variable through photocatalytic action, and

the wettability of the surface is changed by the action of the photocatalyst.

225. (New) The method for pattern formation according to claim 224, wherein the pattern-wise exposure of the photocatalyst-containing layer is carried out by light beam exposure.

226. (New) The method for pattern formation according to claim 224, wherein the pattern-wise exposure of the photocatalyst-containing layer is carried out by exposure through a photomask.

227. (New) The method for pattern formation according to claim 224, wherein the pattern-wise exposure of the photocatalyst-containing layer is carried out while heating the structure for pattern formation.

228. (New) An element comprising the structure for pattern formation according to claim 1, and a functional layer provided on the structure for pattern formation in its areas corresponding to a pattern, of the structure for pattern formation, obtained by the pattern-wise exposure according to claim 224.

229. (New) The element according to claim 228, wherein the functional layer is a layer containing at least a metal.

230. (New) An element produced by transferring a functional layer onto another substrate, the functional layer being provided on a structure for pattern formation in its areas corresponding to a pattern, of the structure for pattern formation, obtained by the pattern-wise exposure according to claim 224.

231. (New) A process for producing an element, comprising the steps of:

providing the structure for pattern formation according to claim 217, and

forming a functional layer provided on the structure for pattern formation in its areas corresponding to a pattern, of the structure for pattern formation, obtained by the pattern-wise exposure according to claim 224.

232. (New) The process for producing an element according to claim 231, comprising the steps of:

coating of a composition for a functional layer onto the whole surface of the structure for pattern formation, and

forming a patterned functional layer on the structure for pattern formation only in its wettability-varied exposed areas by utilizing the repellency of unexposed areas.

233. (New) The process for producing an element according to claim 231, comprising the steps of:

instillation of a composition for a functional layer onto the whole surface of the structure for pattern formation, and

forming a patterned functional layer on the structure for pattern formation only in its wettability-varied exposed areas by utilizing the repellency of unexposed areas.

234. (New) The process for producing an element according to claim 231, wherein the functional layer is formed on the structure for pattern formation by ejecting a composition for a functional layer through a nozzle to the wettability-varied areas.

235. (New) The process for producing an element according to claim 234, wherein the ink-jet system is used for the nozzle ejection.

236. The process for producing an element according to claim 231, comprising the steps of:

adhesion of a composition for a functional layer onto the whole surface of the structure for pattern formation, and

forming the functional layer by transferring the composition for a functional layer in pattern-wise only to the exposed wettability-varied area, due to a difference in adherence of exposed area and unexposed area, on another substrate.

237. (New) The process for producing an element according to claim 231, wherein the functional layer is formed on the structure for pattern formation by thermal or pressure transfer from a film coated with a composition for a functional layer or a roll coated with a composition for a functional layer.

238. (New) The process for producing an element according to claim 231, wherein the functional layer is formed on the structure for pattern formation by film formation utilizing electroless plating.

239. (New) The process for producing an element according to claim 231, comprising the steps of:

laminating a composition for a functional layer onto the whole surface of the structure for pattern formation, and

removing the functional layer in its unexposed areas to form a patterned functional layer.

240. (New) The process for producing an element according to claim 239, wherein the functional layer is formed on the structure for pattern formation by coating a composition for a functional layer.

241. (New) The process for producing an element according to claim 239, wherein the functional layer is formed on the structure for pattern formation by film formation of a composition for a functional layer, utilizing vacuum.

242. (New) The process for producing an element according to claim 239, wherein the functional layer is formed on the structure for pattern formation by transferring a composition for a functional layer.

243. (New) The process for producing an element according to claim 239, wherein the functional layer is formed on the structure for pattern formation by ejecting a composition for a functional layer through a nozzle.

244. (New) The process for producing an element according to claim 243, wherein the ejecting through a nozzle is done by an ink-jet system.

245. (New) The process for producing an element according to claim 239, wherein the unexposed area of the functional layer is removed by a solvent.

246. (New) The process for producing an element according to claim 239, wherein the unexposed area of the functional layer is removed by adhering and peeling off a substrate which adhesive layer is formed.